

NOTES:

1. MATERIALS

- HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0  
COLOR: BLACK
- EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0  
COLOR: SEE TABLE
- TERMINAL - COPPER ALLOY

2. PLATING - SEE TABLE IN SHEET 5 & 6.

3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.  
(MEASURED OVER P.C. PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.

5. REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE SPECIFICATIONS.

6. PRODUCT SHALL BE PACKED IN TRAY.

7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

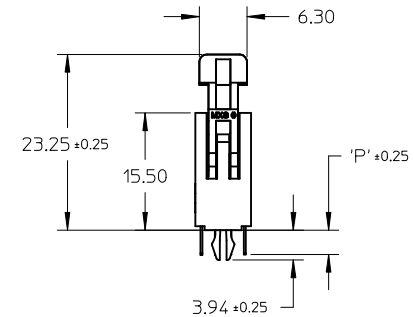
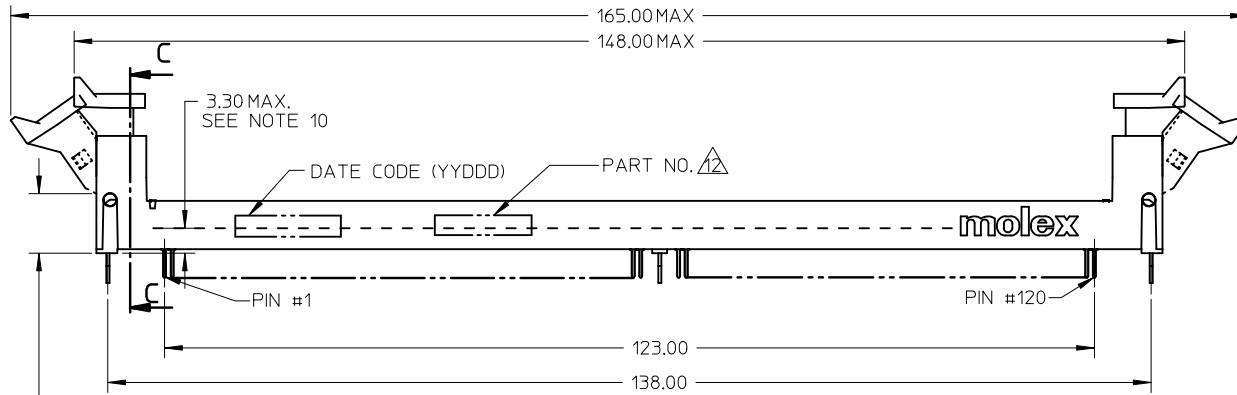
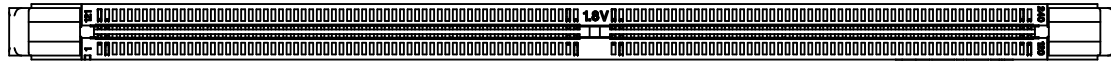
8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.

9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.

10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

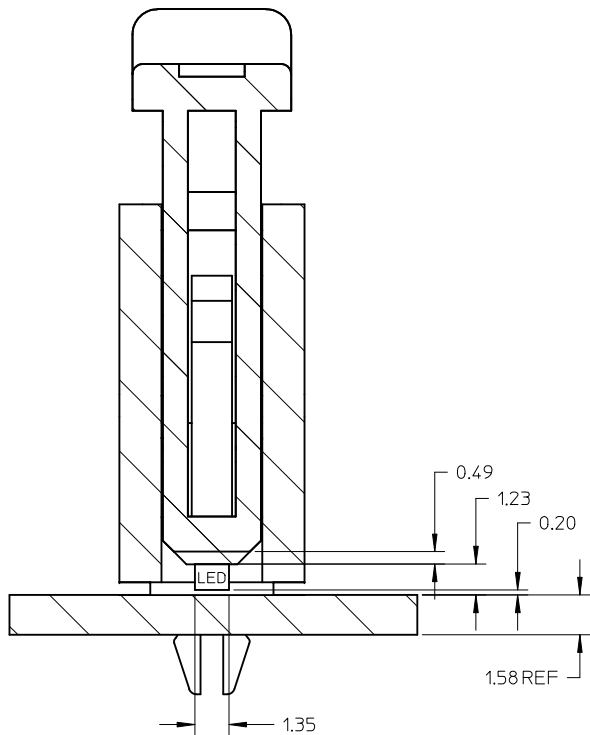
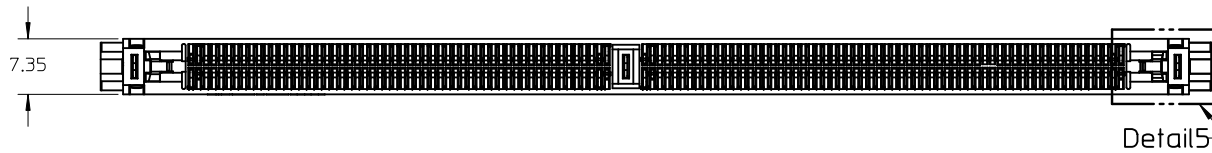
▲ PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-\*\*\*\*



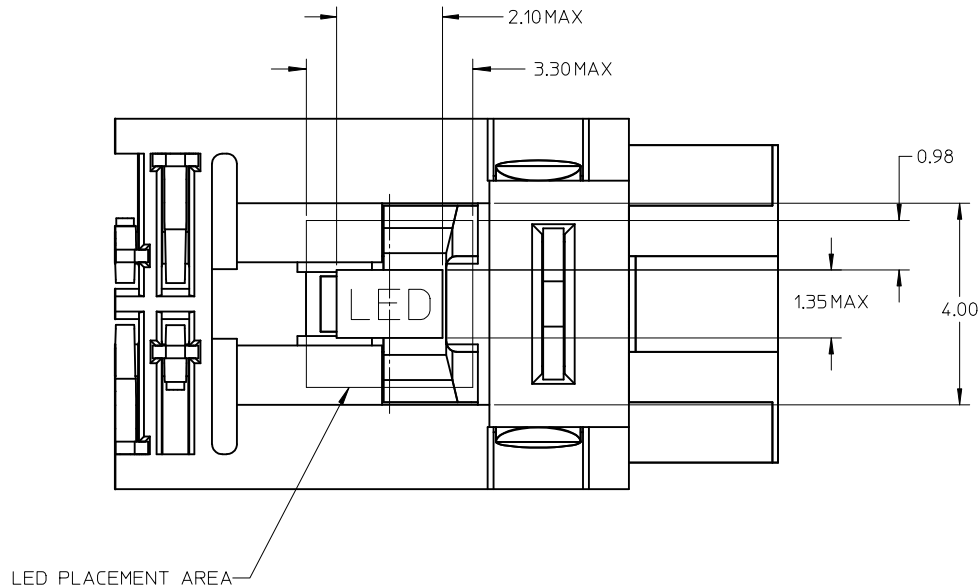
5.00 MIN  
LATCH KEEP  
OUT AREA

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH CHKD: CGTAN APPR: SILENI 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS $\nabla_A=0$ $\nabla_C=0$ $\nabla_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CGOH	2002/05/09	DDR2 DIMM, 100MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS			
	2 PLACES	± 0.20	± ---	DSOH	2002/07/22	(FORKLOCK VERSION)				
	1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED				
	ANGULAR ± 5 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SKTOH	2002/07/23	DOCUMENT NO.		SHEET NO.	
D2		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SD-87705-001		1 OF 6		

10 9 8 7 6 5 4 3 2 1



SECTION C-C



LED PLACEMENT AREA

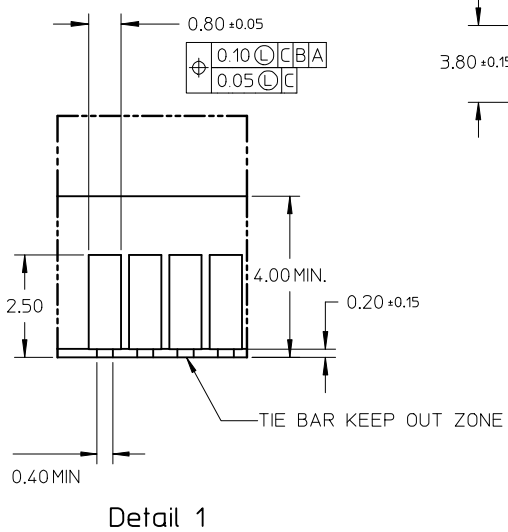
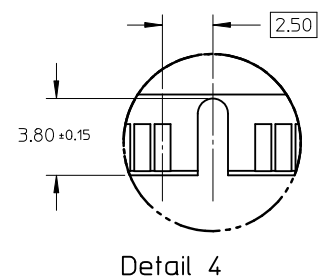
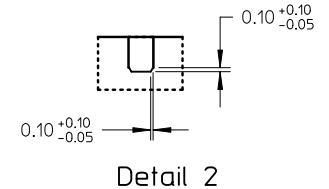
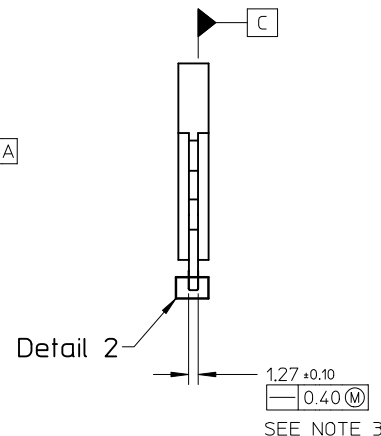
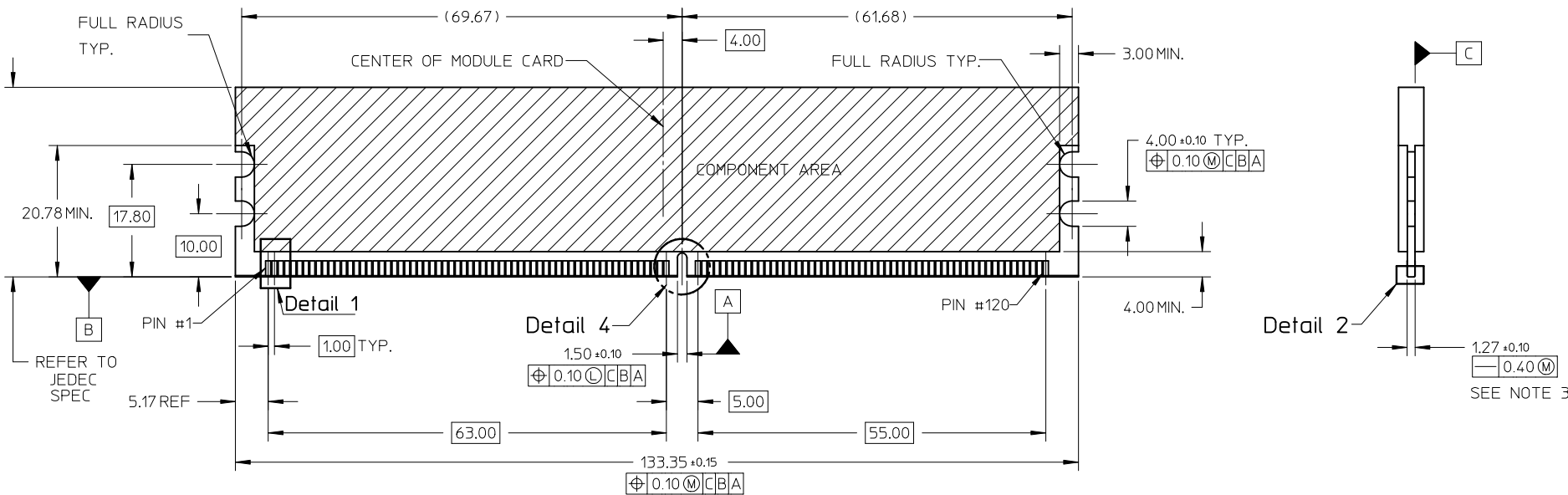
Detail 5

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH CHKD: CGTAN APPR: SILENI	DESCRIPTION 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm	INCH	MM ONLY	NTS	METRIC			
			4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE		
			3 PLACES	± ---	± ---	CGOH	2002/05/09	DDR2 DIMM, 100MM PITCH		
	2 PLACES	± 0.20	± ---	CHECKED BY	DATE	240 CKTS				
	1 PLACE	± ---	± ---	DSOH	2002/07/22	(FORKLOCK VERSION)				
				APPROVED BY	DATE	MOLEX INCORPORATED				
				SKTOH	2002/07/23	MATERIAL NO.				
						DOCUMENT NO.				
						SD-87705-001				
						SHEET NO.				
						2 OF 6				
						SIZE				
						A3				
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

RECOMMENDED MODULE LAYOUT

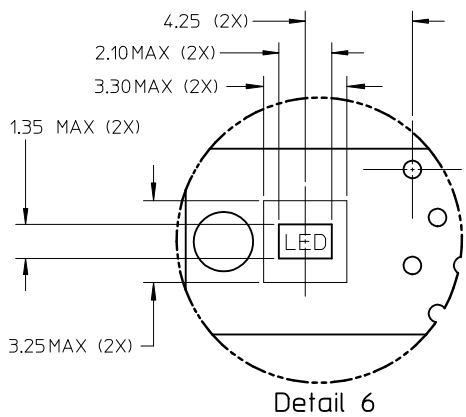


NOTES:  
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

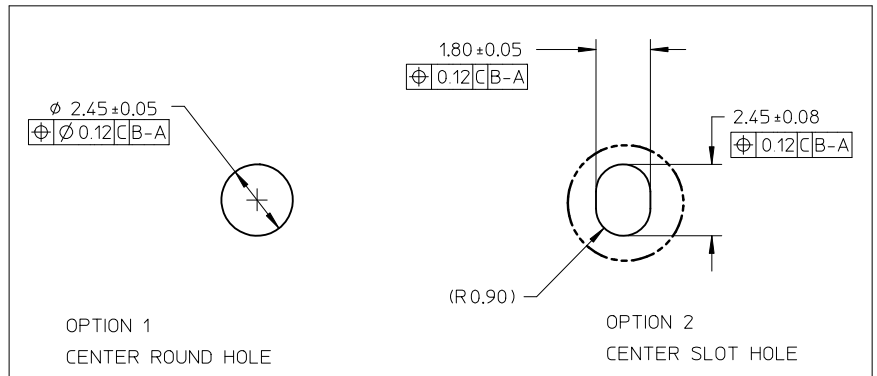
ADDED OPTION EC NO: S2012-0025 DRW: CTEH CHKD: CGTAN APPR: SILENI 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)				
		3 PLACES ± --- ± ---		CHECKED BY DSOH	DATE 2002/07/22	MOLEX INCORPORATED				
		2 PLACES ± 0.20 ± ---		APPROVED BY SKTOH	DATE 2002/07/23	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87705-001	SHEET NO. 3 OF 6		
1 PLACE ± --- ± ---		ANGULAR ± 5 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS										

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



Detail 6

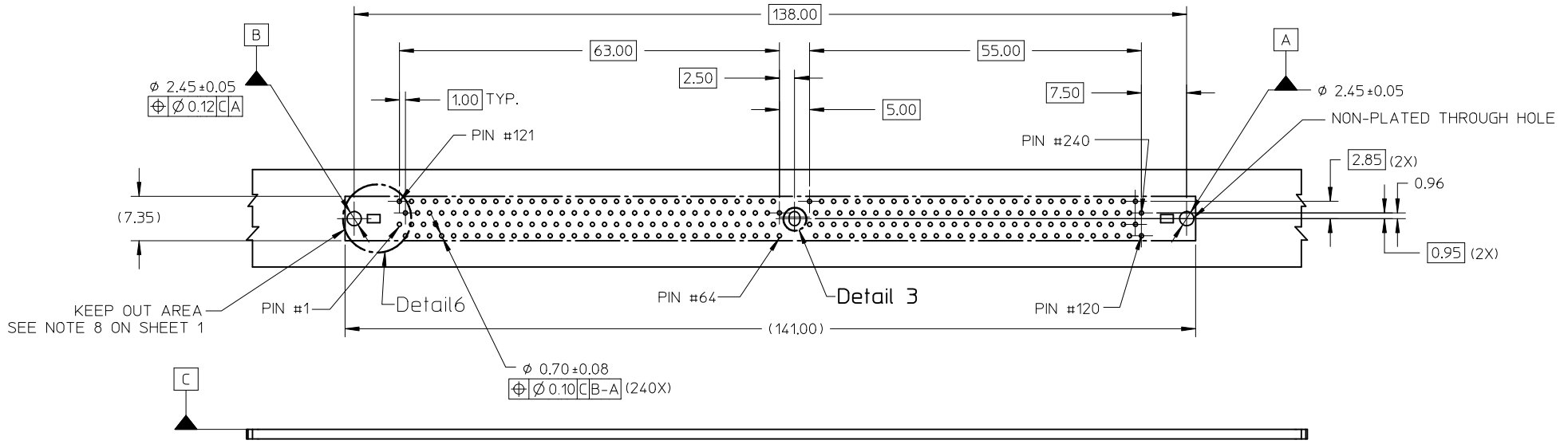


OPTION 1  
CENTER ROUND HOLE

OPTION 2  
CENTER SLOT HOLE

Detail 3

(SEE RECOMMENDED THICKNESS IN TABLE)  
RECOMMENDED PCB LAYOUT  
CONNECTOR SIDE



KEEP OUT AREA  
SEE NOTE 8 ON SHEET 1

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH CHKD: CGTAN APPR: SILENI 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DIMENSION STYLE MM ONLY DRAWN BY: CGOH CHECKED BY: DSOH APPROVED BY: SKTOH DATE: 2002/05/09 DATE: 2002/07/22 DATE: 2002/07/23	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE TABLE	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)	MOLEX INCORPORATED	
	D2	REV	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	DOCUMENT NO. SD-87705-001	SHEET NO. 4 OF 6	
	MOLEX INCORPORATED						

9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR	LUBRICATION
87705-0021	CENTER (1.8V)	2.67	1.57	0.38uM / 15 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	NATURAL	NO
87705-1021		3.18	2.36			
87705-1053		3.66				
87705-0031		2.67	1.57	0.03uM / 1 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE		
87705-1031		3.18	2.36			
87705-0051		2.67	1.57	0.76uM / 30 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE		
87705-1051		3.18	2.36			
87705-3061						YES

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH 2009/11/16 CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC	
			DRAWN BY: CGOH    DATE: 2002/05/09 CHECKED BY: DSOH    DATE: 2002/07/22 APPROVED BY: SKTOH    DATE: 2002/07/23	TITLE	DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
			MATERIAL NO.    DOCUMENT NO.    SHEET NO. SEE TABLE    SD-87705-001    5 OF 6	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-5051	CENTER (1.8V)	2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	CLEAR
87705-5151		3.18	2.36		
87705-6151		3.18	2.36	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-9101		2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	

ADDED OPTION EC NO: S2012-0025 2009/11/16 DRW: CTEH CHKD: GTAN 2011/07/14 APPR: SILENI 2011/07/14	REV D2	DESCRIPTION QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
							DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)			
							CHECKED BY DSOH	DATE 2002/07/22				
								APPROVED BY SKTOH	DATE 2002/07/23	MOLEX INCORPORATED		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
					SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					